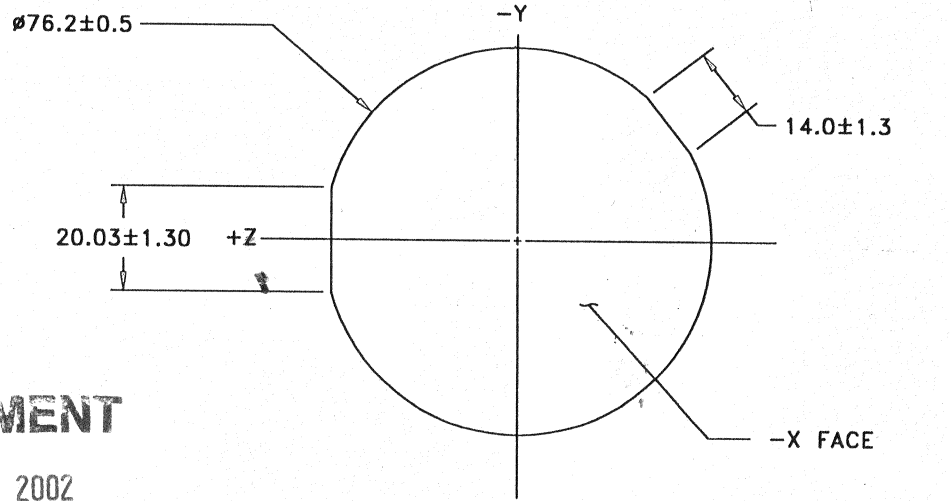


NOTES:

- 1.0.0 ORIENTATIONS
- 1.1.0 WAFER SURFACE IS NORMAL TO X AXIS WITHIN $\pm 0.5^\circ$.
- 1.2.0 WAFER FLAT
- 1.2.1 PRIMARY FLAT, PERPENDICULAR TO THE +Z AXIS $\pm 0.5^\circ$
- 1.2.2 SECONDARY FLAT 135° CLOCKWISE FROM THE PRIMARY FLAT WHEN VIEWING THE -X POLISHED FACE.
- 2.0.0 SURFACES
- 2.1.0 SIDE 1
- 2.1.1 POLISHED, NO PITS OR SCRATCHES ALLOWED WITHIN THE WORKING AREA (ENTIRE WAFER DIAMETER LESS 1.0MM AROUND THE EDGE). INSPECTED USING UNAIDED EYE WITH REFLECTED LIGHT.
- 2.2.0 SIDE 2
- 2.2.1 GROUND. Ra 0.5um - 0.7um.
- 2.3.0 EDGE
- 2.3.1 ALL EDGES ROUNDED WITH A R=0.70 \pm 0.08 RADIUS.
- 2.3.2 NO CHIPS GREATER THAN 0.5mm IN PENETRATION AND 1.0mm IN LENGTH.
- 2.4.0 FLATNESS
- 2.4.1 WARP \leq 50um. MEASURED IN THE FREE STATE.
- 2.4.2 T.T.V < 10.0um. DEFINED AS THE DIFFERENCE BETWEEN THE LOWEST AND HIGHEST ELEVATION OF THE WAFER, MEASURED IN THE CLAMPED STATE.

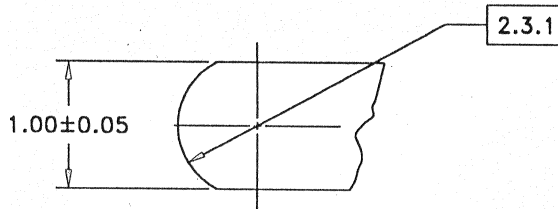
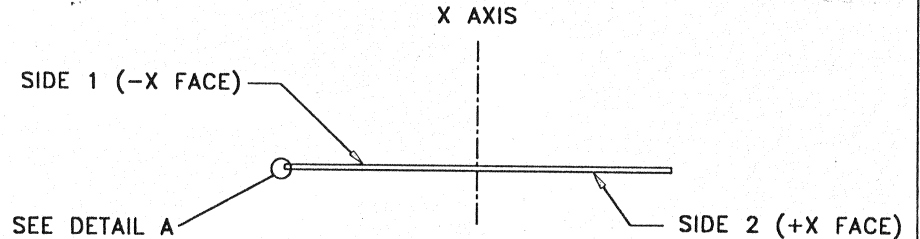
REVISIONS					
ZONE	REV	DESCRIPTION	ECO NO.	APPD.	DATE
ALL	D	UPDATE PER EO	9610	SR	12/15/97



DOCUMENT

FEB 22 2002

CONTROL



DETAIL A
SCALE: 25X

FINISH: SEE NOTES		CONTRACT NUMBER	
MATERIAL: LN		DR. RATZLIFF	12/15/97
SPEC. NO. UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MM		CHK.	
TOLERANCES		APPD.	
INCHES	MILLIMETERS	DESIGN ACTIVITY APPROVAL:	
.XX \pm .01	X.XX \pm 0.25	CUSTOMER APPROVAL:	
.XXX \pm .005	X.XXX \pm 0.125	DO NOT SCALE DRAWING	
.XXXX \pm .0020			
ANG \pm .5°			



Crystal Technology, Inc.
A Siemens Company

TITLE: LN WAFER, 76.2 ϕ X1.0 (X) POL/GRD 20.0 +Z FLT 14.0 SEC		
SIZE: A	DWG. NO. 97-00663-01	REV. D
SCALE: N/A	SH. 1 OF 1	

THIS DOCUMENT IS THE PROPERTY OF CRYSTAL TECHNOLOGY, INC. IT IS NOT TO BE REPRODUCED OR DISCLOSED IN WHOLE OR IN PART OTHER THAN BY EMPLOYEES OF CRYSTAL TECHNOLOGY AND ITS CONTRACTED REPRESENTATIVES AND DISTRIBUTORS. ANY EXCEPTION REQUIRES THE WRITTEN CONSENT OF AN AUTHORIZED REPRESENTATIVE OF CRYSTAL TECHNOLOGY.